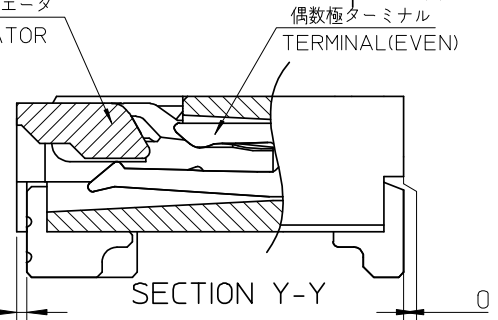
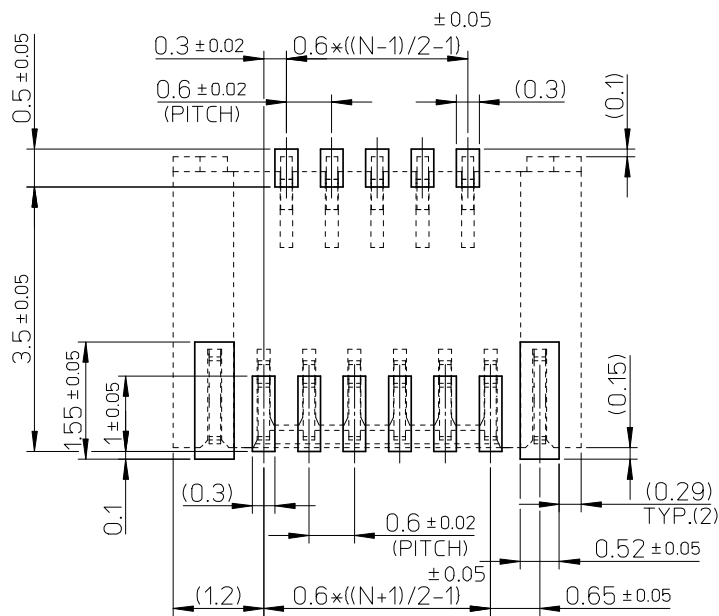


15.6	14.4	15.0	17.4	501912-5190	501912-5110	51
14.4	13.2	13.8	16.2	501912-4790	501912-4710	47
13.8	12.6	13.2	15.6	501912-4590	501912-4510	45
12.6	11.4	12.0	14.4	501912-4190	501912-4110	41
12.0	10.8	11.4	13.8	501912-3990	501912-3910	39
11.4	10.2	10.8	13.2	501912-3790	501912-3710	37
10.8	9.6	10.2	12.6	501912-3590	501912-3510	35
10.2	9.0	9.6	12.0	501912-3390	501912-3310	33
8.4	7.2	7.8	10.2	501912-2790	501912-2710	27
7.8	6.6	7.2	9.6	501912-2590	501912-2510	25
7.2	6.0	6.6	9.0	501912-2390	501912-2310	23
6.6	5.4	6.0	8.4	501912-2190	501912-2110	21
4.8	3.6	4.2	6.6	501912-1590	501912-1510	15
D	C	B	A	EMBOSSED-TAPE PKG ORDER No.	MATERIAL No.	CIRCUIT

MODEL No. 501912-**10



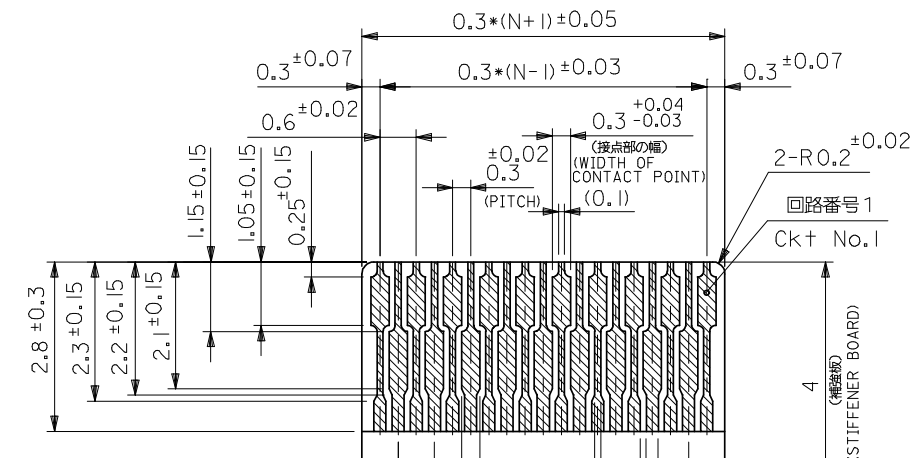
REVISED EC NO: J2008-3324 DRWN: HTAGAMI 2008/03/25 CHKD: KAKAHASHI 2008/04/07 APPR: KAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	15:1	METRIC	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	±0.25	M.HAYASHI	2005/07/28	0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING	
30 OVER	±0.3	CHECKED BY	DATE			
		APPROVED BY	DATE	MOLEX INCORPORATED		
		MATERIAL NO.	SEE TABLE	DOCUMENT NO.	SD-501912-001	SHEET NO. 1 OF 2
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



参考基板レイアウト図
(マウント面)
(MOUNTING SIDE)

注記 NOTES

- 使用材料 MATFRIAL
 ハウジング : 耐熱性樹脂 ガラス充填 UL94V-0
 HOUSING : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0
 アクチュエータ : 耐熱性樹脂 ガラス充填 UL94V-0
 ACTUATOR : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0
 ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ
 TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.
 金具 : 銅合金 (t=0.15), ニッケル下地スズメッキ
 FITTING NAIL : COPPER ALLOY, TIN OVER NICKEL PLATING.
 ハウジングに黒点がある場合が有りますが、問題はありません。
- ソルダーテール半田付け面、及び金具半田付け面の平坦度 : 0.1mm MAXIMUM.
 COPLANARITY OF SOLDER TAILS AND FITTING NAILS TO BE 0.1mm MAXIMUM.
- ELV AND RoHS COMPLIANT.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

打抜き方向は導体側から補強板側を推奨いたします。
 導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨致します。
 補強フィルム材質はポリイミドを推奨します。
 接着剤は熱硬化接着剤を推奨します。

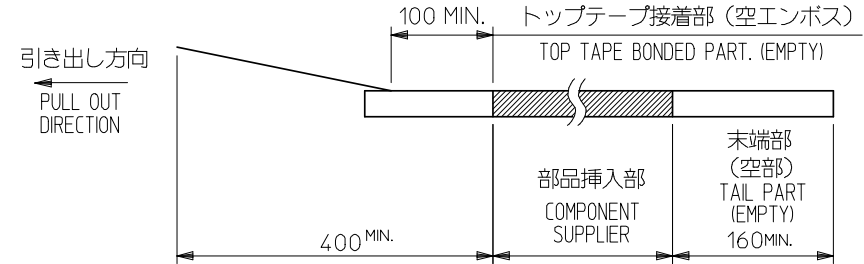
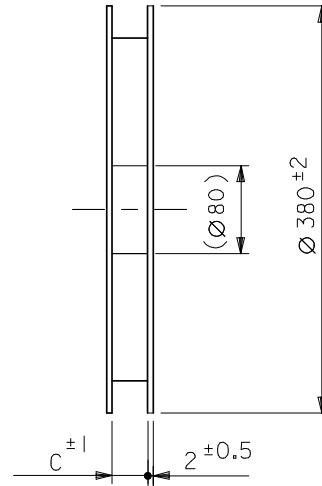
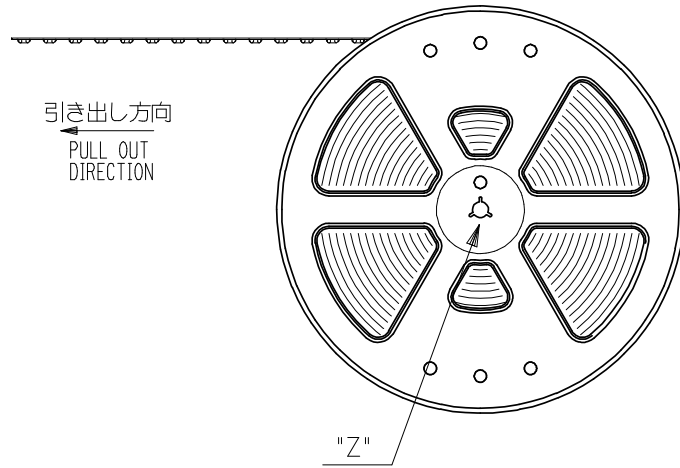
ABOUT FPC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPEC :
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER
 RECOMMENDED MATERIAL :
 STIFFENER FILM : POLYIMIDE
 BONDING AGENT : THERMOSETTING BONDING AGENT

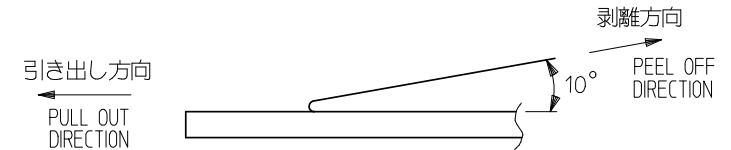
REVISED EC NO: J2008-3324 DRAWN: HTAGAMI 2008/03/25 CHKD: TAKAHASHI 2008/04/07 APPR: KAKAHASHI 2008/04/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ----	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/07/28	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING				
		10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/07/28	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/07/28	DOCUMENT NO. SD-501912-001				
REV	SIZE A3	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



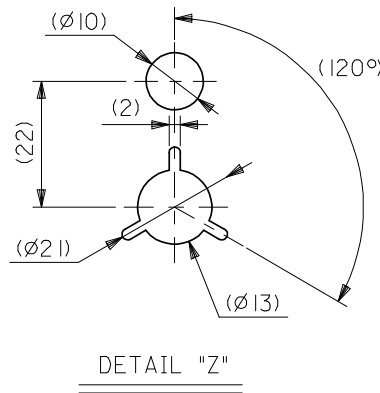
- トップテープの剥離強度：60±35gf (0.25N～0.93N) (剥離方向は下図参照) 尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 65gf±30gf (0.25N～0.93N) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.) THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



5. 材料(MATERIAL)

キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYREN)
 トップテープ (TOP TAPE) : PET, PE, PEF
 リール(REEL) : ポリスチレン(PS) <リサイクル材を含む>
 POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>

- C寸法は SHEET 2-4を参照下さい。
SEE SHEET 2-4(DIMENSION C).
- ELV AND RoHS COMPLIANT.



DETAIL "Z"

REVISED EC NO: J2008-3324 T DRWN:HTAGAMI 2008/03/25 CH'KD:KTAKAHASHI 2008/04/07 APPR:KTAKAHASHI 2008/04/07 REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	501912-**-90	MODEL NO.
	10 UNDER ±0.2		DRAWN BY DATE M. HAYASHI 2005/10/11		TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 OVER 30 UNDER ±0.25		CHECKED BY DATE H. HIRATA 2005/10/11			MOLEX MOLEX INCORPORATED	SHEET NO. 1 OF 4
	30 OVER ±0.3		APPROVED BY DATE M. SASAO 2005/10/11		DOCUMENT NO. SD-501912-002		
	ANGULAR ±3 °		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 4		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

F

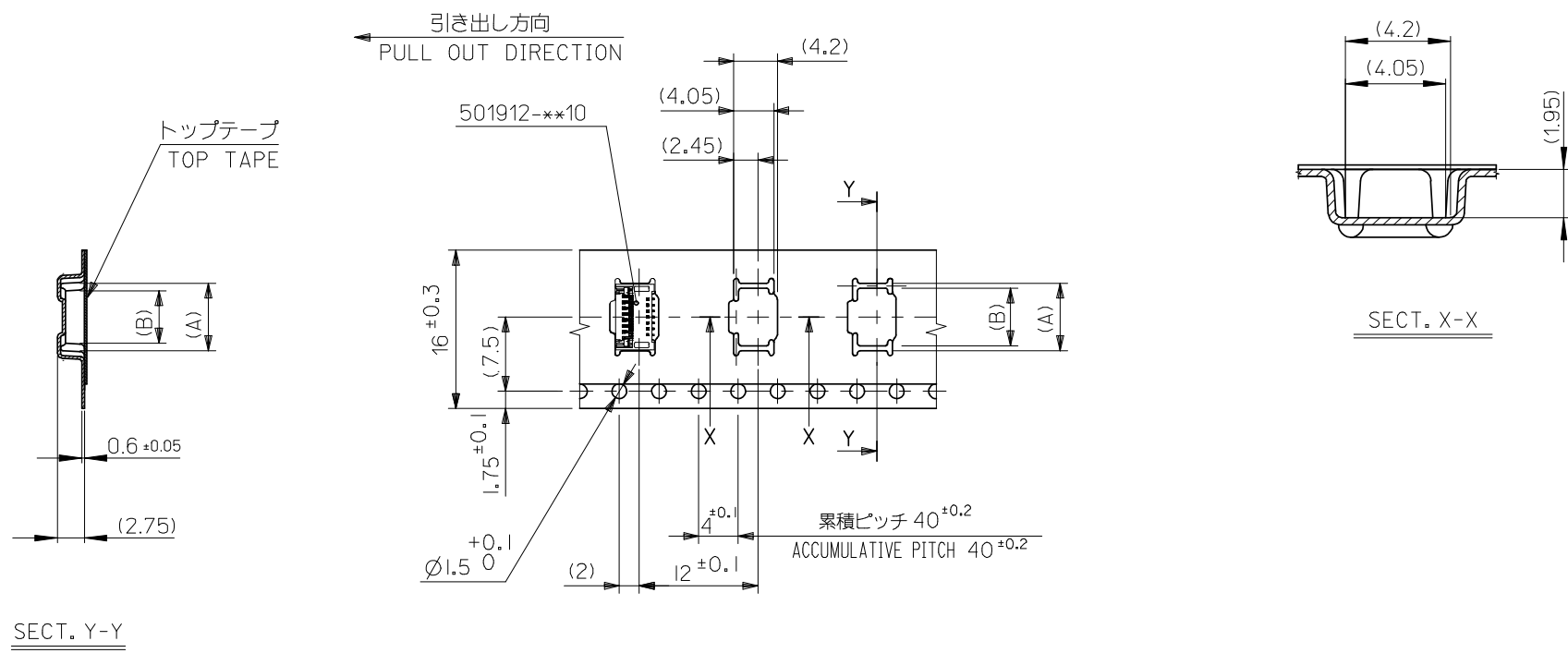
E

D

C

B

A



16 mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	17.5	4.6	6.8	501912-1590	15
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**-90	MODEL No.

REVISED EC NO: J2008-3324 DRWN:HTAGAMI 2008/03/25 CHKD:KTAKAHASHI 2008/04/07 APPR:KTAKAHASHI 2008/04/07 T REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED		
	ANGULAR ±3 °		MATERIAL NO. SEE TABLE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

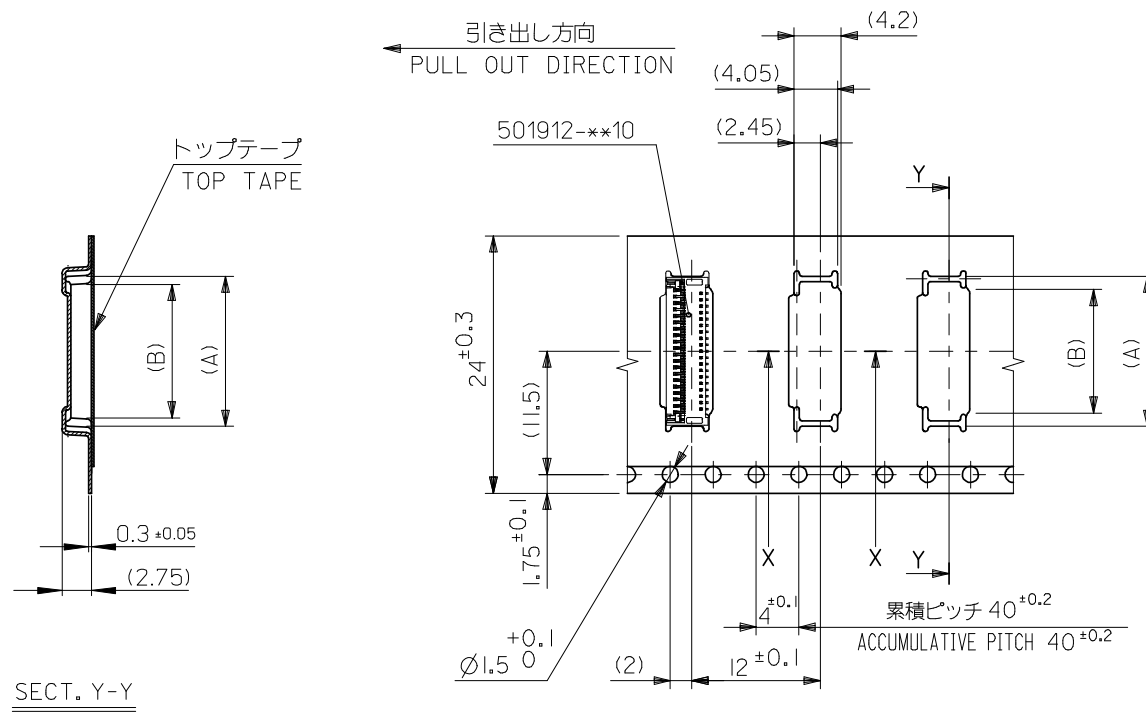
E

D

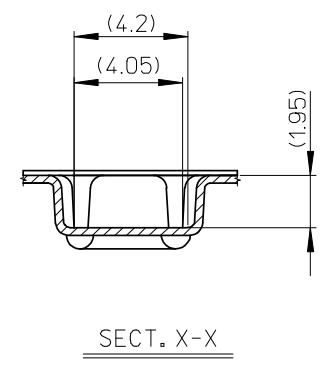
C

B

A



SECT. Y-Y

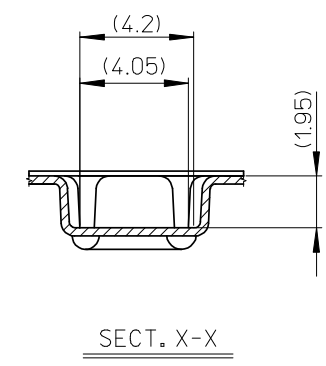
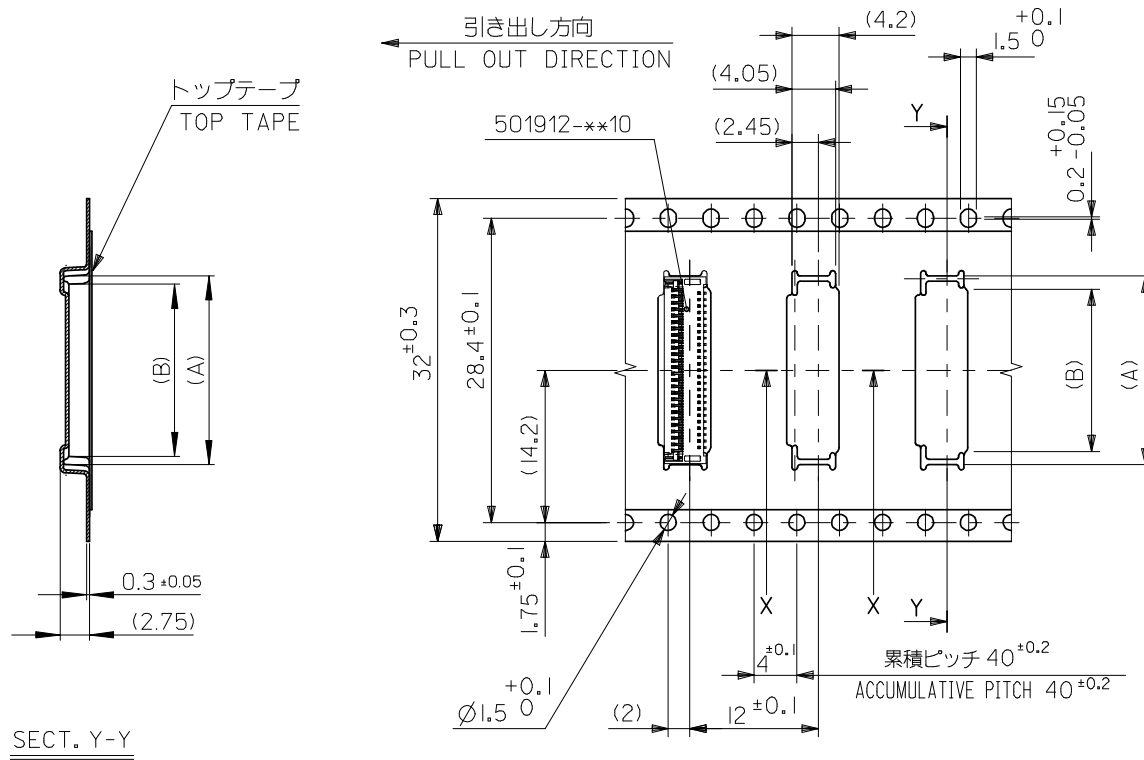


SECT. X-X

24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	25.5	12.4	14.6	501912-4190	41	
		11.8	14.0	501912-3990	39	
		11.2	13.4	501912-3790	37	
		10.6	12.8	501912-3590	35	
		10.0	12.2	501912-3390	33	
		8.2	10.4	501912-2790	27	
		7.6	9.8	501912-2590	25	
		7.0	9.2	501912-2390	23	
		6.4	8.6	501912-2190	21	
キャリアテープ幅 CARRIER TAPE WIDTH		C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**-90	MODEL No.	

REVISED EC NO: J2008-3324 DRWN: HTAGAMI 2008/03/25 CHKD: KTAKAHASHI 2008/04/07 APPR: KTAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING			
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11				
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO. SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

32	33.5	15.4	17.6	501912-5190	51
		14.2	16.4	501912-4790	47
		13.6	15.8	501912-4590	45
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**90	MODEL No.

REVISED EC NO: J2008-3324 T DRWN: H. TAGAMI 2008/03/25 CH'KD: K. TAKAHASHI 2008/04/07 APPR: K. TAKAHASHI 2008/04/07 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING			
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11				
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501912-002		4 OF 4		
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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